PRESS RELEASE

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Contact: Jan Vardaman
(512) 372-8887

Emerging Market for Low-Density Panel FO Analyzed

Large area fan-out (FO) remains a hot topic in the industry. There is some confusion over the term “panel” because IC package substrates are processed in panels. The main driver for large area FO panel development is cost reduction because more parts can be processed in a batch. TechSearch International’s latest Advanced Packaging Update report divides the panel market into high-density RDL (≤2µm L/S with multiple RDLs) versus low-density (>5µm L/S with ≤3 RDLs). The report highlights FO-WLP panel activities at major companies and reports on consortia progress and future plans. Applications for large area panels are discussed. A market forecast is provided for low-density panels and panel capacity is included.

TechSearch International’s new report examines the packages inside Huawei’s Mate 30 5G to see how Huawei has been able to use fewer U.S. components. Recent announcements of high-performance package offerings from TSMC are described. Trade-offs in high-performance packaging are discussed. Quarterly and annual OSAT financial trends are presented. A special section examines EMI shielding offerings and applications. The latest APU is a 42-page report with full references and an accompanying set of 44 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on twitter @Jan_TechSearch and on LinkedIn.